

Date: 5/26/2017

PRODUCT CHANGE NOTIFICATION #10041

Notification of: PCIe Dip Solder Series Processing Temperature update.

Date Change Effective: 5/22/2017

Explanation of change:

Updated solder processing to wave/manual soldering only.

Reason for change: Cap required to prevent card slot deformation during reflow processing.

Anticipated impact on fit, form, or function (positive/negative): Positive

Parts/Products affected:

(G,N)_E140DHHN-T9__ (DWG 11040-K)
(G,N)_E115DHHN-T9__ (DWG 11041-K)
(G,N)_E__DHHN-T9__ (DWG 11045-K)
G_E__DHHN-T7_1 (DWG 12180-B)
G_E115DHHN-T7_1 (DWG 12181-B)
G_E140DHHN-T7_1 (DWG 12182-B)

Parts prior to change will remain active for purchase?

Yes No

New or revised parts are interchangeable to the previous part applications?

Consult factory for part with cap for reflow process.

Engineering Approval:



Truong Tran

5/26/2017

(Signature)

(Printed Name)

(Date)

Distribution: Website, Distributors, Customers, Internal

Information regarding this change notification and other previously issued change notifications can be found on our website: www.sullinscorp.com/product-change-notification. If you have any questions or concerns, please contact us at Support@sullinscorp.com or call us at (760) 744-0125.

Sincerely,

Sullins Connector Solutions